



- (51) **International Patent Classification:**
H01L 21/285 (2006.01) *H01L 21/768* (2006.01)
- (21) **International Application Number:**
PCT/US2015/060477
- (22) **International Filing Date:**
12 November 2015 (12.11.2015)
- (25) **Filing Language:** English
- (26) **Publication Language:** English
- (30) **Priority Data:**
62/078,598 12 November 2014 (12.11.2014) US
- (71) **Applicant:** ONTOS EQUIPMENT SYSTEMS [US/US];
343 Meadow Fox Lane, Chester, New Hampshire 03036
(US).
- (72) **Inventor:** SCHULTE, Eric; 100 Las Alturas Road, Santa
Barbara, California 93103 (US).
- (74) **Agents:** GROOVER III, Robert O. et al.; P.O. Box 520,
Wills Point, Texas 75169 (US).
- (81) **Designated States** (*unless otherwise indicated, for every
kind of national protection available*): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY,

BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM,
DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,
HN, HR, HU, ID, IL, IN, IR, IS, JP, KE, KG, KN, KP, KR,
KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, ME, MG,
MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM,
PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC,
SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN,
TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

- (84) **Designated States** (*unless otherwise indicated, for every
kind of regional protection available*): ARIPO (BW, GH,
GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ,
TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU,
TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE,
DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU,
LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK,
SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ,
GW, KM, ML, MR, NE, SN, TD, TG).

Published:

- with international search report (Art. 21(3))
- before the expiration of the time limit for amending the
claims and to be republished in the event of receipt of
amendments (Rule 48.2(h))

(54) **Title:** SIMULTANEOUS HYDROPHILIZATION OF PHOTORESIST SURFACE AND METAL SURFACE PREPARATION: METHODS, SYSTEMS, AND PRODUCTS

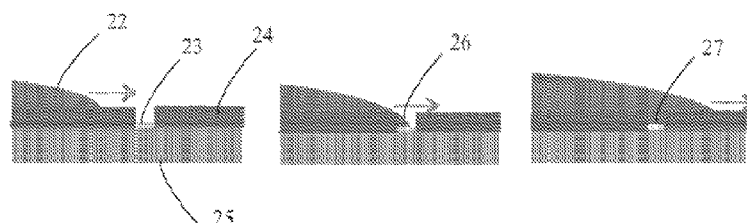


FIG. 4

(57) **Abstract:** Methods and systems for using the downstream active residuals of a reducing-chemistry atmospheric plasma to provide multiple advantages to pre-plating surface preparation with a simple apparatus. As the downstream active species of the atmospheric plasma impinge the substrate surface, three important surface preparation processes can be performed simultaneously: 1. Organic residue is removed from the surface of the plating base. 2. Oxidation is removed from the surface of the plating base. 3. All surfaces on the substrate are highly activated by the downstream active residuals thus creating a highly wettable surface for subsequent plating operations.

